| | N CONNECTING S INDUSTRIES® MALE TALES MALE TALES MALE TALES MALE TALES MALE TALE MALE TALE MALE TALE MALE TALE MALE TALE COMP | osition Dec PC, Bannockb n-American co | c laration ourn, Illinois. A opyright conver | ll rights reserved untions. | under both | This docume level parts, t | ent is a declara he declaration | ation of encon | f the substances npasses all lowe | within th er level ma | e manufactur aterials for wi | er listed i hich the n | tem. Note: nanufactur | if the item is an as er has engineering | sembly with lowe responsibility. |
|-------------------------|--|--|---|-----------------------------|-------------------------|-------------------------------|---|-------------------|--------------------------------------|---------------------------------|---------------------------------|---------------------------|--------------------------|--|----------------------------------|
| 1752-21.1 | IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x | | | | Form Type Distribute | | | | | neous Materi | erials and Mfg Information | | | | |
| Supplie | r Information | | | | | | | | | | | | | | |
| Company name* Company u | | | | ny unique ID | | | Unique ID Authority | | | | | Response Date* | | | |
| onsemi | | | | | | | | | | | | 2024-04-25 | | | |
| Contact N | lame | Title - Contact | | | | Phone - Contact* | | | | | Email - Contact* | | | | |
| Product-Env-Stewards | | | Product Enviro Compliance | | | | NA | | | | Product-Env-Stewards@onsemi.com | | | | |
| Authorize | ed Representative* | Title - Representative | | | | Phone - Representative* | | | | Email - Representative* | | | | | |
| Product- | Env-Stewards | Product Enviro Compliance | | | | NA | | | | Product-Env-Stewards@onsemi.com | | | | | |
| | Requester Item Number Mfr Item 2SB1203 | | | | | | Effective Date Version Manufacturing S 2024-04-25 CNG | | uring Site | Weight* 326.57 | | UOM | Unit Type | | |
| | | | | | | | | | | | | mg | Each | | |
| Aanufa | cturing Proccess Informa | tion | | · | | | | | | | | | | | |
| | Terminal Plating / Grid Array Material | | Terminal Base Alloy J-STD-02 | | J-STD-020 MSI | L Rating | Peak Process Body Tempe | | Body Temperatu | ture Max Time at Peak ? | | Temperat | ure Nun | nber of Reflow Cyc | les |
| contains Bi | | | CU Alloy NA | | | | 0 C 30 | | | seconds 3 | | | | | |
| Comments | 6 | | | | | | | | | | | | | | |
| | | | | | | | | | | | | | | | |
| or more | information regarding material | composition | please refer to | page 3 | | | | | | | | | | | |

| RoHS Material Composition Declaration | | | | Declaration Type * | Detailed | | | | | | |
|--|---|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | | mium (Cr6+), Polybrominated Biphenyls (Pl | | dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et | | | | | | | |
| cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company | ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the | henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg | nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co | e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica | ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of | | | | | | |
| RoHS Declaration * 4 - Item(| s) does not contain RoHS restricted subst | ances per the definition above except for sele | ected exempt | ions Supplier Acceptance | * Accepted | | | | | | |
| Exemption: 7a: Lead in high melting temp | Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). | | | | | | | | | | |
| Exemption List Version | EL-2011/534/EU | | | | | | | | | | |
| Declaration Signature | | | | | | | | | | | |
| Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester. | | | | | | | | | | | |
| Supplier Digital Signature | astislav Drska | Le | | | | | | | | | |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|----------------------------|------------------|--------|----------|-----------------|
| Die | 1.04 | mg | Supplier | Silicon (Si) | 7440-21-3 | | 1.04 | mg |
| Die Attach Solder | 0.49 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.0123 | mg |
| | | | А | Lead (Pb) | 7439-92-1 | 7a | 0.4533 | mg |
| | | | Supplier | Tin (Sn) | 7440-31-5 | | 0.0245 | mg |
| lead Frame | 191.37 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.3827 | mg |
| | | | Supplier | Tin (Sn) | 7440-31-5 | | 0.2679 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 190.7193 | mg |
| Iold Compound-Black | 129.7 | mg | | Brominated epoxy resin | proprietary data | | 1.8158 | mg |
| | | | Supplier | Epoxy Phenol Resin | Proprietary Data | | 5.8365 | mg |
| | | | В | Antimony Trioxide (Sb2O3) | 1309-64-4 | | 1.1673 | mg |
| | | | Supplier | Carbon Black (C) | 1333-86-4 | | 1.297 | mg |
| | | | Supplier | Fused Silica (SiO2) | 60676-86-0 | | 97.275 | mg |
| | | | Supplier | Ortho-Cresol Novolac Resin | 29690-82-2 | | 22.049 | mg |
| | | | Supplier | Silica Crystalline (SiO2) | 14808-60-7 | | 0.2594 | mg |
| Plating | 3.34 | mg | В | Bismuth (Bi) | 7440-69-9 | | 0.02 | mg |
| | | | Supplier | Tin (Sn) | 7440-31-5 | | 3.32 | mg |
| Wire Bond - Au | 0.63 | mg | Supplier | Gold (Au) | 7440-57-5 | | 0.63 | mg |